



Thermal Silicone Pad



特色 Characteristic

- 具導熱性 Thermal conductive
- 高柔軟性及高壓縮性 High soft and compressible
- 自黏性佳 **Excellent natural tack**
- 高耐電壓值 Good insulator
- 可當緩衝材使用 Shock & vibration absorber
- 多種厚度可選擇 Available in varies thickness

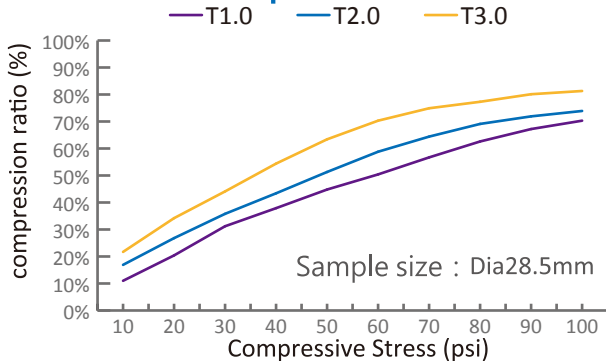
適用範圍 Usage

IC, CPU, GPU, MOS, LED, M/B, PSU, PS, Heat Sink, LCD-TV, CASE, NB, PC, HDD, DDR Module, DVD, etc.

物性 Properties	MP-19	MP-19Y	MP-19YFB	Unit	Test Method
顏色 Color	Grey	Yellow	Yellow+Yellow	---	Visual
厚度 Thickness	0.25~25	0.25~25	0.5~25	mm	ASTM D374
導熱係數 Thermal conductivity	1.9	1.6	1.6	W/mk	ASTM D5470
比重 Specific Gravity	1.7±0.2	1.7±0.2	2.0±0.2	g/cm ³	ASTM D792
延展率 Elongation	<250±10	<250±10	<1	%	ASTM D412
抗拉強度 Tensile Strength	10±3	3±3	70±5	Kgf/cm ²	ASTM D412
硬度 Hardness	15±3	4±3	4±3	Shore A	ASTM D2240
重量損失 Weight Loss	<1	<1	<1	%	200°C(48hrs)
體積電阻 Volume Resistivity	>10 ¹³	>10 ¹³	>10 ¹⁴	ohm•cm	ASTM D257
耐電壓 Insulation Strength	>5.0	>5.0	>10	KV	ASTM D149
耐溫範圍 Continuous Use Temp	-45~200	-45~200	-45~200	°C	---

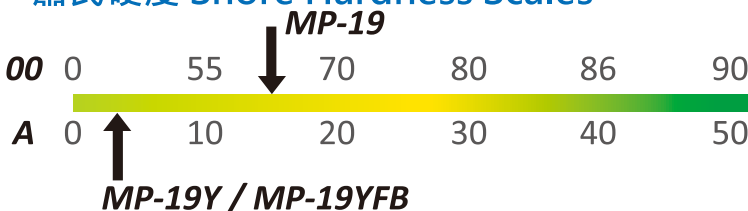
* 測試片標準厚度為1mm以上。 The thickness of the test piece is at least 1 mm.

壓縮測試 Compression Test

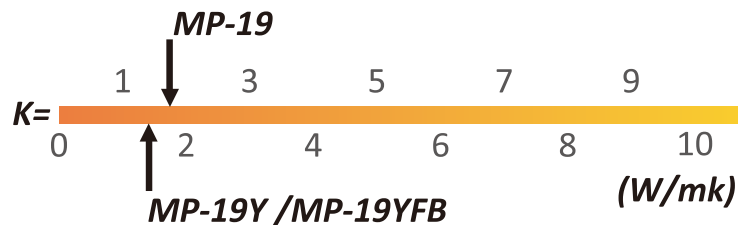


The compression ratio of MP-19 T2.0 at 50 psi is about 51.3%.

蕭氏硬度 Shore Hardness Scales



導熱係數 Thermal conductivity



備註 Remark

- *可添加玻璃纖維增強機械性 (P/N: MP-19FG、MP-19YFG、MP-19YFGFB)
Can add with fiberglass reinforced.
- *可外加玻璃纖維布增強機械性 (P/N: MP-19FB、MP-19YFB)
Can add with fiberglass reinforced.
- *雙面皆可背膠 (A1 / A2)
Can add with adhesive on one or two sides.